



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

Name / Model #1: HP Compaq t5135/5530 Thin Client

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. To remove the secure USB compartment cover (see Figure 1):
 - a. On rear of the thin client, remove the screw that secures the compartment cover to the unit (1).
 - b. On the front of the unit, push the compartment cover about 1/2–inch toward the back of the unit (2).
 - c. Remove the cover from the unit by first lifting the rear (screw side) of the cover, and then lifting the cover off the unit (3).
2. To remove the access panel (see Figure 2):
 - a. Remove the secure compartment cover (1).
 - b. Remove the two back panel screws that secure the access panel to the chassis (2).
 - c. Slide the access panel about 1/4–inch toward the front of the unit, and then lift the access panel up and off the unit (3).
3. To remove the metal side cover (see Figure 3):
 - a. Remove the three screws that secure the metal side cover to the chassis (1).
 - b. Lift the metal side cover up and off the unit (2).
4. To remove the battery, pull back on the clip (1) that is holding the battery in place, and then remove the battery (2) (see Figure 4).
5. To remove the system board:
 - a. Remove the five screws that secure the system board to the thin client chassis (see Figure 5).
 - b. Remove the four screws that secure the heatsink to the system board, and then remove the heatsink (see Figure 5).
 - c. Cut the wire that connects from the system board to the chassis.
 - d. Pull the system board and rear connector panel out of the rear of the unit. The rear connector panel and system board will remain together.
6. Cut the four capacitors from the system board as shown in Figure 5 (see Figure 6).

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the secure USB compartment cover



FIGURE 2: Removing the access panel

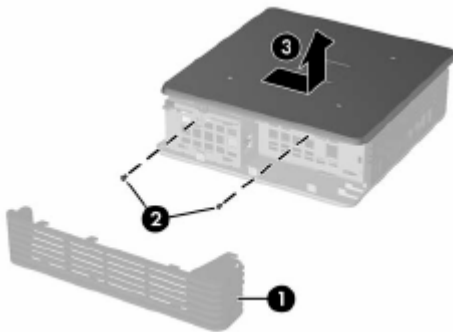


FIGURE 3: Removing the metal side cover

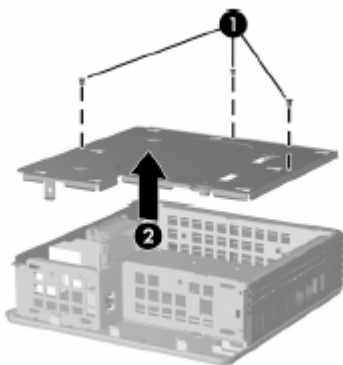


FIGURE 4: Battery removal

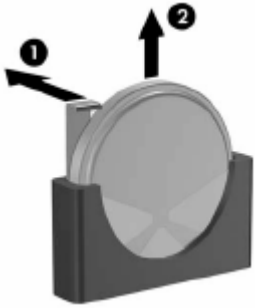


FIGURE 5: System board screw and heatsink screw locations

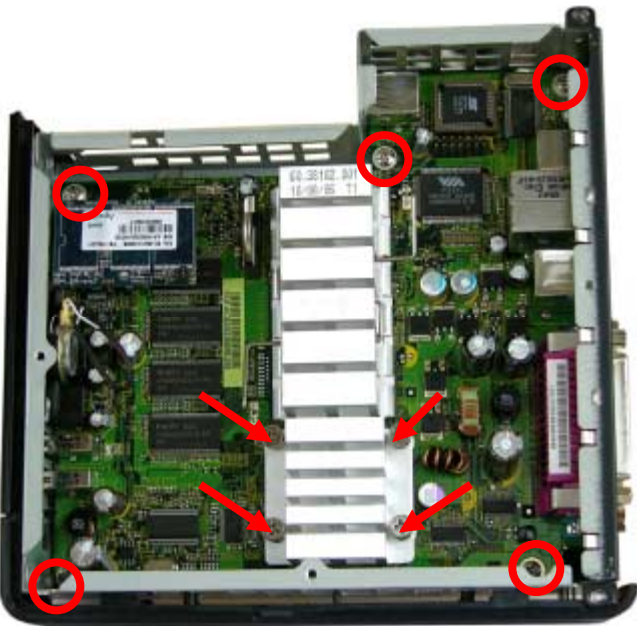


FIGURE 6: Capacitors to cut

